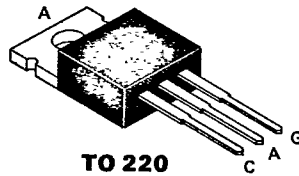


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S2512BH - S2512NH SCR'S

25 A 200-800 V 25-50 mA

The S2512 series silicon controlled rectifiers are high performance glass passivated PNP devices. These parts are intended for general purpose high current applications where moderate gate insensitivity is required.

Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Part Nr. | Symbol | Min. | Max. | Unit | Test Conditions |
|-----------------------------------|----------------|--------------|------|------|------------------|---|
| Repetitive Peak Off State Voltage | S2512BH | | 200 | | V | |
| | S2512DH | V_{DRM} | 400 | | V | $T_j = -40^\circ\text{C}$ to 125°C |
| | S2512MH | V_{RRM} | 600 | | V | $R_{GK} = 1\text{K}\Omega$ |
| | S2512NH | | 800 | | V | |
| On-State Current | | $I_{T(RMS)}$ | 25 | | A | All Conduction Angles $T_C = 85^\circ\text{C}$ |
| Average On-State Current | | $I_{T(AV)}$ | 16 | | A | Half Cycle, $\Theta = 180^\circ$, $T_C = 85^\circ\text{C}$ |
| Nonrept. On-State Current | | I_{TSM} | 270 | | A | Half Cycle, 60 Hz |
| Nonrept. On-State Current | | I_{TSM} | 250 | | A | Half Cycle, 50 Hz |
| Fusing Current | | I^2t | 310 | | A ² s | $t = 10\text{ ms}$, Half Cycle |
| Peak Gate Current | | I_{GM} | 4 | | A | 10 μ s max. |
| Peak Gate Dissipation | | P_{GM} | 10 | | W | 10 μ s max. |
| Gate Dissipation | | $P_{G(AV)}$ | 1 | | W | 20 ms max. |
| Operating Temperature | | T_j | -40 | 125 | $^\circ\text{C}$ | |
| Storage Temperature | | T_{stg} | -40 | 125 | $^\circ\text{C}$ | |
| Soldering Temperature | | T_{slid} | | 250 | $^\circ\text{C}$ | 1.6 mm from case, 10 s max. |

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Min. | Max. | Unit | Test Conditions |
|----------------------------------|-------------------|------|------|------------|---|
| Off-State Leakage Current | I_{DRM}/I_{RRM} | | 2.5 | mA | @ $V_{DRM} + V_{RRM}$, $R_{GK} = 1\text{K}\Omega$, $T_j = 125^\circ\text{C}$ |
| Off-State Leakage Current | I_{DRM}/I_{RRM} | | 10 | μ A | @ $V_{DRM} + V_{RRM}$, $R_{GK} = 1\text{K}\Omega$, $T_j = 25^\circ\text{C}$ |
| On-State Voltage | V_T | | 1.58 | V | at $I_T = 50\text{ A}$, $T_j = 25^\circ\text{C}$ |
| On-State Threshold Voltage | $V_{T(TO)}$ | | 0.85 | V | $T_j = 125^\circ\text{C}$ |
| On-State Slope Resistance | r_T | | 16.5 | m Ω | $T_j = 125^\circ\text{C}$ |
| Gate Trigger Current | I_{GT} | 25 | 50 | mA | $V_D = 7\text{ V}$ |
| Gate Trigger Voltage | V_{GT} | | 2.5 | V | $V_D = 7\text{ V}$ |
| Holding Current | I_H | | 75 | mA | $R_{GK} = 1\text{K}\Omega$ |
| Latching Current | I_L | | 150 | mA | $R_{GK} = 1\text{K}\Omega$ |
| Critical Rate of Voltage Rise | dv/dt | 500 | | V/ μ s | $V_D = .67 \times V_{DRM}$, $R_{GK} = 1\text{K}\Omega$, $T_j = 125^\circ\text{C}$ |
| Critical Rate of Current Rise | di/dt | 100 | | A/ μ s | $I_G = 250\text{ mA}$, $di_G/dt = 2.5\text{ A}/\mu\text{s}$, $T_j = 125^\circ\text{C}$ |
| Gate Controlled Delay Time | t_{gd} | | 500 | ns | $I_G = 250\text{ mA}$, $di_G/dt = 2.5\text{ A}/\mu\text{s}$ |
| Commutated Turn-Off Time | t_q | | 50 | μ s | $T_C = 85^\circ\text{C}$, $V_D = .67 \times V_{DRM}$, $V_R = 35\text{ V}$, $I_T = I_{T(AV)}$ |
| Thermal Resistance junc. to case | $R_{\theta jc}$ | | 1.55 | K/W | |
| Thermal Resistance junc. to amb. | $R_{\theta ja}$ | | 60 | K/W | |

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